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## **AMENDMENTS TO THE CLAIMS**

## 1-8. (Canceled)

- 9. (New) A binding compound comprising an antigen binding site from a substantially pure or recombinant antibody, wherein the antibody specifically binds to a polypeptide comprising mature SEQ ID NO:20 or a fragment thereof.
- 10. (New) The binding compound of claim 9, wherein the binding compound blocks the interaction between OX2 and OX2R.
- 11. (New) The binding compound of claim 9, wherein the binding compound is a Fv, Fab, or Fab<sub>2</sub> fragment.
- 12. (New) The binding compound of claim 9, wherein the binding compound is conjugated to a chemical moiety.
  - 13. (New) The binding compound of claim 9, wherein the attached to a solid substrate.
- 14. (New) The binding compound of claim 13, wherein the solid substrate is a bead or a plastic membrane.
- 15. (New) The binding compound of claim 9, wherein the binding compound binds the polypeptide of SEQ ID NO:20 or a fragment thereof, with a  $K_d$  of at least 30  $\mu$ M.
- 16. (New) The binding compound of claim 9, wherein the polypeptide comprising mature SEQ ID NO:20 is a fusion protein.
- 17. (New) The binding compound of claim 9, wherein the binding compound is in a sterile composition.

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18. (New) The binding compound of claim 9, wherein the binding compound is labeled with a detectable label.

- 19. (New) The binding compound of claim 18, wherein the label is a fluorescent label or a radioactive label.
- 20. (New) The binding compound of claim 9, wherein the binding compound binds the polypeptide comprising SEQ ID NO:20 or a fragment thereof when it is denatured.
- 21. (New) The binding compound of claim 9, wherein the antibody is a polyclonal antibody.
- 22. (New) The binding compound of claim 9, wherein the antibody is raised against a polypeptide comprising SEQ ID NO:20 or some fragment thereof.
  - 23. (New) A kit comprising:
    - a) the binding compound of claim 9;
    - b) a compartment for the binding compound; and
    - c) instructions for use or disposal of reagents in the kit.